ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	burn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration er	on of the su compasses	bstances v all lower	vithin the manufactur level materials for w	er listed it hich the m	em. Note: i anufacture	if the item is an as r has engineering	sembly with low responsibility.
752-21.1 IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information													
Company name*	Company uni	que ID	e ID U			Unique ID Authority				Response Date*			
onsemi						2023-06-08							
Contact Name Title - Contact					Phone - Contact*				Email - Contact*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title			e - Representative			Phone - Representative*			Email - Representative*				
roduct-Env-Stewards	Product Envir	duct Enviro Compliance NA Product-Env-Stewards@				vards@onsemi.co	rds@onsemi.com						
Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	Manufacturing Site		١	Weight*	UOM	Unit Type	
	AR0143 A0-TRB	ATSC00XUE BR	1.3MP 1/4 CIS			2023-06-08		М	1Y5	1	.97.96	mg	Each
Ianufacturing Proccess Information	tion												
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020			J-STD-020 MSI	Rating	Peak Proce	ss Body Te	emperature	e Max Time at Peak	Temperat	ure Numl	ber of Reflow Cyc	les	
SnAgCu CU Alloy 3						260		С	30	secon	ds 3		
omments													
TTENTION: MSL 3 Rated item require	s Bake and I	Dry Pack (after	electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	28.5	mg		Misc.	proprietary data		0.1083	mg
			Supplier	Silicon (Si)	7440-21-3		28.1096	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2822	mg
Die Attach	0.97	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.3638	mg
			Supplier	Ethylene Glycol	107-21-1		0.0097	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0291	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.2037	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3638	mg
Imaging Lens	34.8	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.8315	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.8315	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.8315	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1834	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.8315	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.8315	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		25.459	mg
Lid Attach	1.75	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.525	mg
			Supplier	Filler (SiO2)	68909-20-6		0.0875	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.5687	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.5687	mg
Mold Compound-Black	45.67	mg		Phenolic Resin	proprietary data		6.8505	mg
			Supplier	Oxirane	39817-09-9		6.8505	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.3701	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4567	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.2288	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.9134	mg
older Ball	33.42	mg	Supplier	Silver (Ag)	7440-22-4		1.0026	mg
			Supplier	Tin (Sn)	7440-31-5		32.2503	mg
			Supplier	Copper (Cu)	7440-50-8		0.1671	mg
Substrate and Solder Mask	52.39	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.5868	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		6.7897	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0786	mg

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	1.2207	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.5868	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.3039	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0052	mg
			Supplier	Acetophenone Derivative	Proprietary Data	1.8284	mg
			Supplier	Carbon Black (C)	1333-86-4	0.3039	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.3039	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	6.2868	mg
		В	Nickel (Ni)	7440-02-0	0.7387	mg	
			Supplier	Gold (Au)	7440-57-5	0.0262	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.6621	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.5868	mg
			Supplier	Copper (Cu)	7440-50-8	19.6253	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	9.4564	mg
Wire Bond - Au	0.46	mg	Supplier	Gold (Au)	7440-57-5	0.46	mg